

RG3J-10

GLASS PASSIVATED JUNCTION RECTIFIER

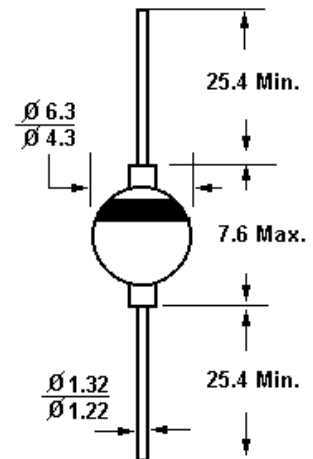
Forward Current – 3.0 Amperes

Features

- Cavity-free glass passivated junction
- High temperature metallurgically bonded construction
- High temperature soldering guaranteed:
350°C/10 seconds, 0.375" (9.5mm) lead length,
5 lbs, (2.3kg) tension

Mechanical Data

- **Case:** Solid glass body.
- **Terminals:** Solder plated axial leads, solderable per MIL-STD-750.Method 2026.
- **Polarity:** Color band denotes cathode end.
- **Mounting Position:** Any
- **Weight:** 0.04 ounce, 1.1 grams.

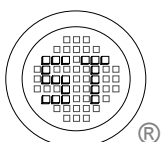


Dimensions in mm

Absolute Maximum Ratings and Characteristics Ratings at 25°C ambient temperature unless otherwise specified.

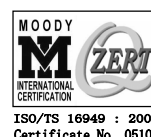
| | Symbols | Value | Units |
|--|-----------------|----------------------------------|--------------------|
| Maximum repetitive peak reverse voltage | V_{RRM} | 400 | Volts |
| Maximum RMS voltage | V_{RMS} | 280 | Volts |
| Maximum DC blocking voltage | V_{DC} | 400 | Volts |
| Maximum average forward rectified current 0.375" (9.5mm) lead length at $T_A=70^\circ\text{C}$ | $I_{F(AV)}$ | 3 | Amps |
| Peak forward surge current 8.3ms single half sine-wave superimposed on rated load (JEDEC method) | I_{FSM} | 125 | Amps |
| Maximum full load reverse current, full cycle average, 0.375"(9.5mm)lead length at $T_A=70^\circ\text{C}$ | $I_{R(AV)}$ | 150 | μA |
| Maximum instantaneous forward voltage at 3A $T_A = 25^\circ\text{C}$ | V_F | 1.3 | Volts |
| Maximum DC reverse current at rated DC blocking voltage | I_R | $T_A = 25^\circ\text{C}$ 5 | μA |
| | | $T_A = 175^\circ\text{C}$ 300 | |
| Typical junction capacitance at 4V, 1MHz | C_J | 40 | pF |
| Typical thermal resistance (Note 1) | $R_{\theta JA}$ | 20 | $^\circ\text{C/W}$ |
| | $R_{\theta JL}$ | 10 | |
| Operating junction temperature range | T_J | -65 to+175 | $^\circ\text{C}$ |
| Storage temperature range | T_S | -65 to+200 | $^\circ\text{C}$ |

Notes: (1) Thermal resistance from junction to ambient and from junction to lead at 0.375"(9.5mm) lead length with both leads attached between heat sink.



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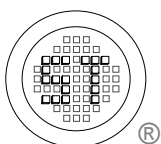
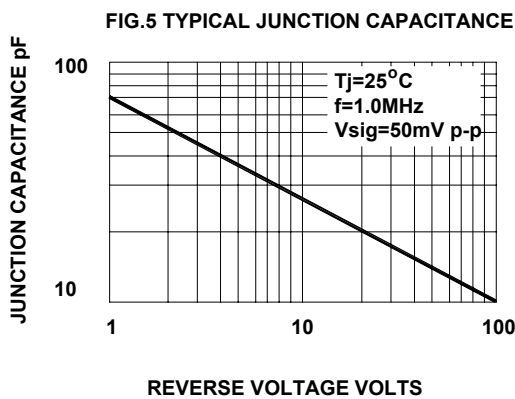
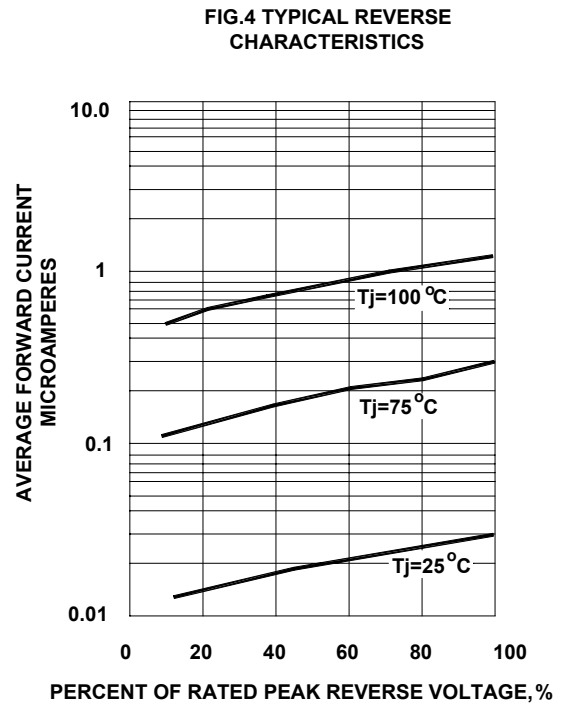
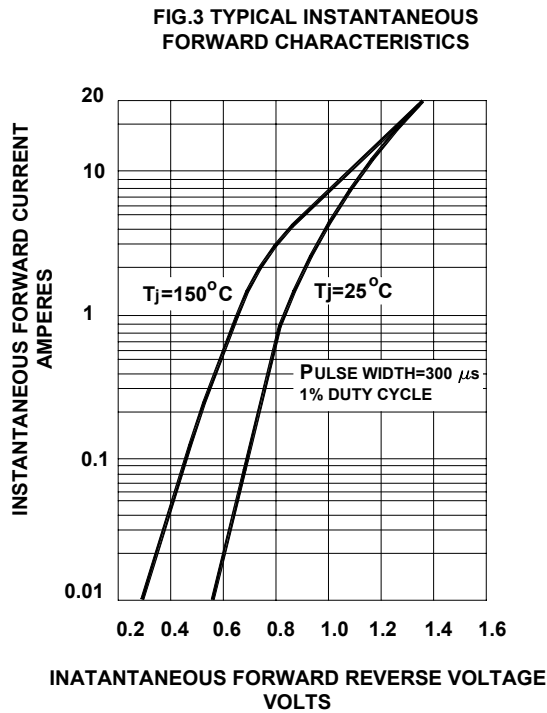
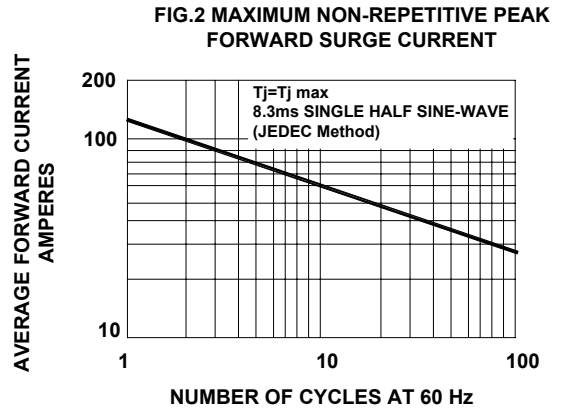
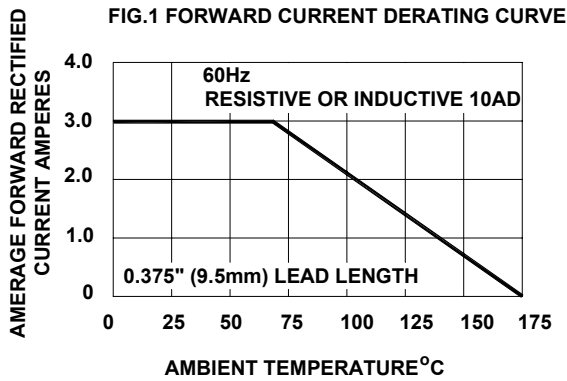
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Dated : 23/06/2003

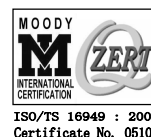
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Ratings and Characteristic Curves ($T_A=25^{\circ}\text{C}$ unless otherwise noted)



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ISO/TS 16949 : 2002
Certificate No. 05103

ISO 14001
Certificate No. 7116

ISO 9001 : 2000
Certificate No. 0507-006-002-001

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